



AI TECHNOLOGY INC
 70 Washington Road
 Princeton Jct., NJ 08550
 (609) 799-9388 fax (609) 799-9308
 E-Mail: ait@aitechnology.com
 Internet: <http://www.aitechnology.com>

TACK FILM
RTC8750

Stress-Free
Reworkable
Electrically Conductive
Epoxy Film Adhesive

IDEAL FOR:

- Substrate and Component**
- Reworkability**
- Mismatched CTE's**

DESCRIPTION:

Room temperature storable tack-film RTC8750 is a reworkable, silver-filled, epoxy film adhesive designed for bonding component and substrate to a mismatched substrate or carrier. This B-staged conductive adhesive offers excellent reworkability at 80-150°C.

RTC8750 has excellent thermal conductivity and its low Tg adhesive imposes minimum thermal stress on bonded parts during thermal cycling or shock testing. This film is reinforced with 1.5 mil fiberglass.

AVAILABILITY:

RTC8750 is available in sheet sizes or as custom preforms. Standard thicknesses are 0.004" and 0.006". Special thicknesses are available.

APPLICATION PROCEDURES:

- (1) Keep product at room temperature for 15 minutes before using.
- (2) Cut to desired size.
- (3) Clean contact surfaces if needed.
- (4) Remove one side of the release liner by peeling up a corner of the release liner. Fold the release liner over, approaching a 180° angle. Pull the release liner quickly, removing it with one stroke. Apply to substrate, then remove other side of release paper and attach die or component. Cure as per schedules.

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer to MSDS for more details.

The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall A.I. Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

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TYPICAL PROPERTIES*

Electrical Resistivity (150 °C/ 30 minut)	<4x10⁻³ ohm-cm
Dielectric Strength (Volts/mil)	Not Applicable
Glass Transition Temp.(°C)	-25
Lap-Shear Strength	1000 psi 6.9 N/mm²
Device Push-off Strength	2400 psi 16.6 N/mm²
Hardness (Type)	82 (A)
Cured Density (gm/cc)	3.5
Thermal Conductivity	45 Btu-in/hr-ft²-°F 6.4 W/m-°C
Linear Thermal Expansion Coeff. (ppm/°C)	110
Maximum Continuous Operation Temp. (°C)	150

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CURE SCHEDULES:

<u>Temperature</u>	<u>Time</u>	<u>Pressure</u>
80°C	8 hr	3-5 psi
100°C	4 hr	3-5 psi
125°C	2 hr	3-5 psi
150°C	1 hr	3-5 psi
200°C	20 min	3-5 psi

The die or component can also be tacked on the substrate at 100°C or higher with 5 psi. When a fillet around the edge of the die or component is observed, the pressure can be released for the rest of the bonding cycle.

SHELF LIFE:

<u>Storage temperature</u>	<u>Shelf Life</u>
0-5°C	1 yr in sealed package